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electrical connections on said photosensitive element, said clear plastic package being clear at all locations within said perimeter.

2. An element as in claim 1, wherein said photosensitive element is a CMOS active pixel sensor.

3. An element as in claim 1, wherein said plastic package is acrylic.

4. (Amended) A method, comprising:

obtaining an image sensor with electrical connections;

forming a clear plastic package for said image sensor, with said image sensor totally encased within said clear plastic package;

forming connections on all edges of a perimeter of said image sensor;

connecting said electrical connections of said image sensor to said connection; and

operating said image sensor to receive light that passes through said clear plastic package.

Please add the following new claims.

5. An element as in claim 1, wherein said clear plastic package is in the shape of a quad flat pack.

A3 ~~6. An element as in claim 1, further comprising a second photosensitive element, receiving incoming light from a different direction than said photosensitive element.~~

~~7. An element as in claim 1, wherein said photosensitive element accumulates charge using a photogate.~~

~~8. A method as in claim 4, wherein said operating comprises accepting light from any of a plurality of different incoming angles.~~

~~9. A method as in claim 8, wherein said clear plastic package is formed of acrylic.~~

~~10. A method as in claim 4, wherein said clear plastic package is formed into the shape of a quad flat pack.~~

B4 ~~11. A method as in claim 4, wherein said obtaining an image sensor comprises obtaining first and second image sensors, and using said first image sensor to acquire light in a first~~

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direction through said clear plastic package and using said second image sensor to acquire light in a second direction through said clear plastic package.

12. An image sensor comprising:

first and second image sensors; and

a clear plastic package for said first and second image sensors, said clear plastic package packaging said first and second image sensors with said first image sensor acquiring light from a first side of said clear plastic package, and said second image sensor acquiring light from a second, opposite side of said clear plastic package.

13. A sensor as in claim 12, wherein said clear plastic package has a perimeter surrounding said first and second image sensors, and an edge of said perimeter including electrical connections to said first and second image sensors.

14. A sensor as in claim 12, further comprising a mounting part, mounting said package such that said edge is coupled to an object of mounting.

15. An image sensor as in claim 12, wherein said first and

second image sensors are CMOS image sensors.

16. An image sensor as in claim 12, wherein said first and second image sensors acquire said image using photogates.

17. A method of acquiring an image, comprising:  
packaging first and second image sensors in a single clear package; and

acquiring an image with said first image sensor from a first side of said package, and acquiring an image from said second image sensor from a second, opposite side of said package.

18. A method as in claim 17, wherein said first side of said package is on the left of a reference line on an object of mounting, and said second side of said package is on the right side of a reference line on said object of mounting.

19. An image sensor, comprising:  
a clear package, having a rectangular outer perimeter with image acquiring surfaces defined within said rectangular outer perimeter; and  
an image sensor, obtaining image information from a first

image acquiring surface and from a second opposite image  
acquiring surface

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20. An image sensor as in claim 19, wherein said image  
sensor includes first and second image sensors facing in  
opposite directions.

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